

Research of Low Gain Avalanche Detectors for High-Precision 4D Tracking in Future Collider Experiments

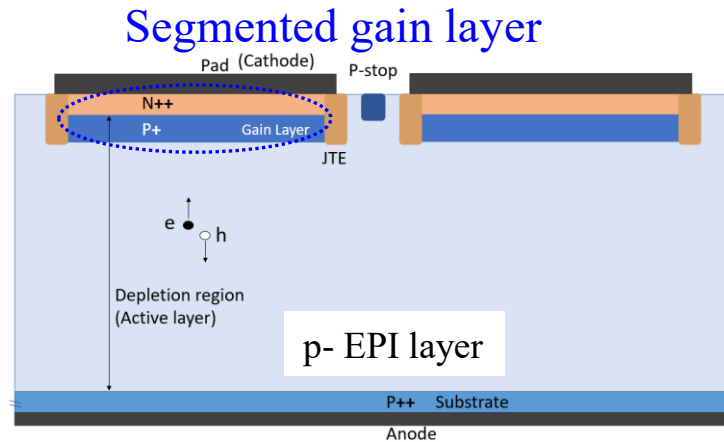
Mei Zhao (IHEP)
zhaomei@ihep.ac.cn

On behalf of IHEP LGAD group & CEPC Silicon Tracker Group

2025-11-19

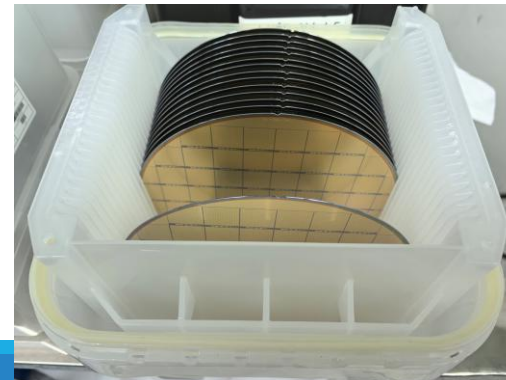
DC-LGAD and AC-LGAD

DC-LGAD (Low-Gain Avalanche Diode)

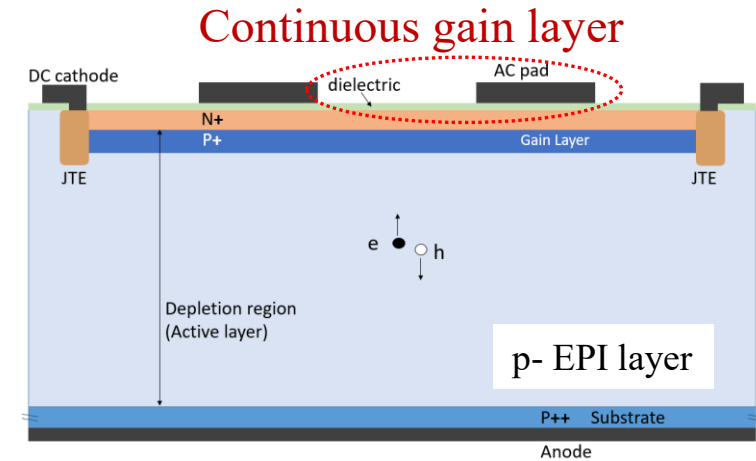


Segmented gain layer

- P+ Gain layer, with Gain:10-50
- The read-out electrode is placed and connected to the N++ layer.
- Large pixel size and dead zone between pixels(JTE, Pstop)



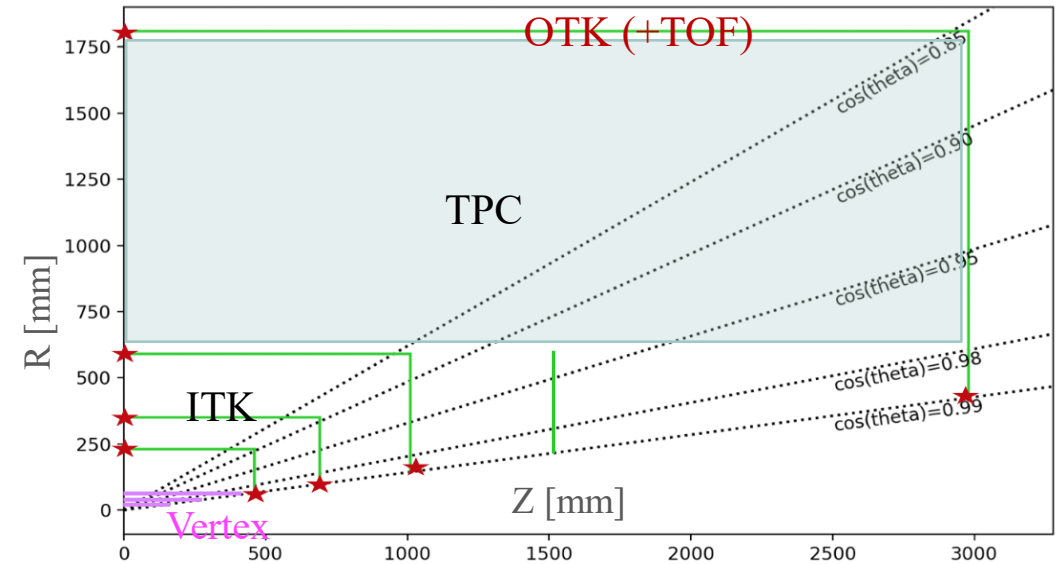
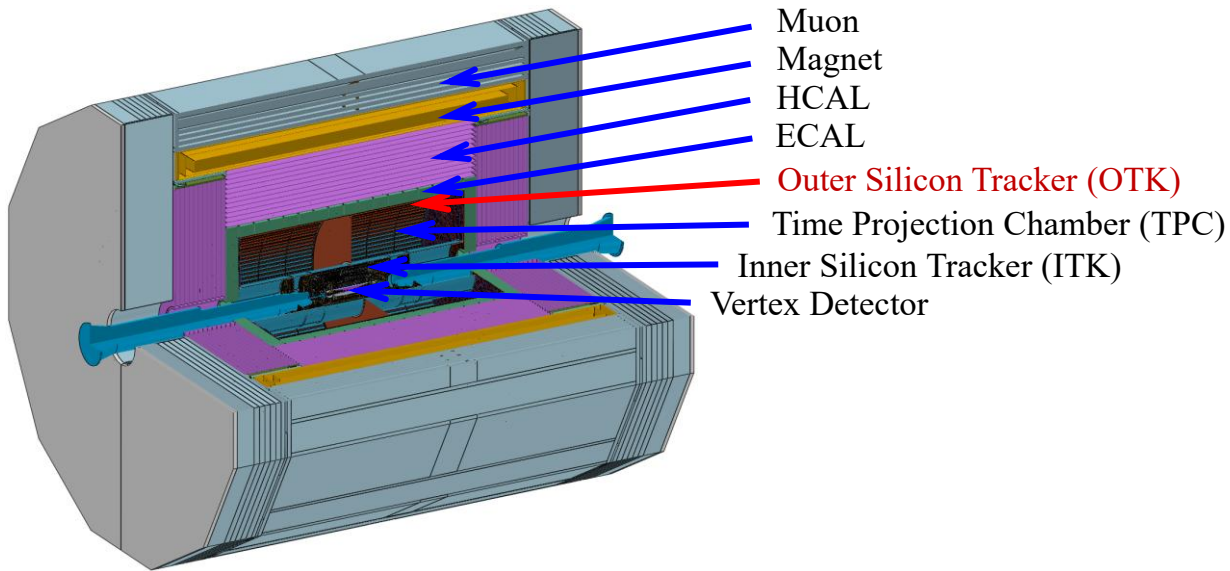
AC-LGAD (AC-coupled LGAD)



Continuous gain layer

- Metal AC readout electrode and a thin dielectric layer (Si_3N_4 , SiO_2) above the N+ layer
- Position information is determined by charge shared between pads.
- Less dead area and better position resolution

CEPC OTK&TOF



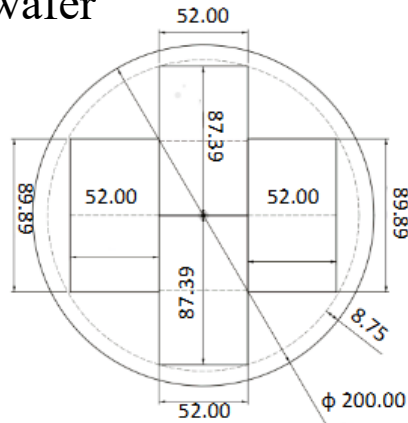
- **CEPC**-- measurement potential for precision tests of SM: Higgs, electroweak physics, flavor physics, QCD/Top
- Produce 10^{12} Z boson at Z pole: Rich flavor physics program
- **The LGAD based OTK (+TOF) detector** will be placed between TPC and ECAL
- Timing detector is complementary to gas detector for PID:
to improve the separation ability: 0-4 GeV for K/pi separation, 0-8 GeV for K/p separation
- **Barrel : $\sim 65 \text{ m}^2$, Endcap 20 m^2**

CEPC Technical Design Report -- Reference Detector:
<https://arxiv.org/abs/2510.05260>

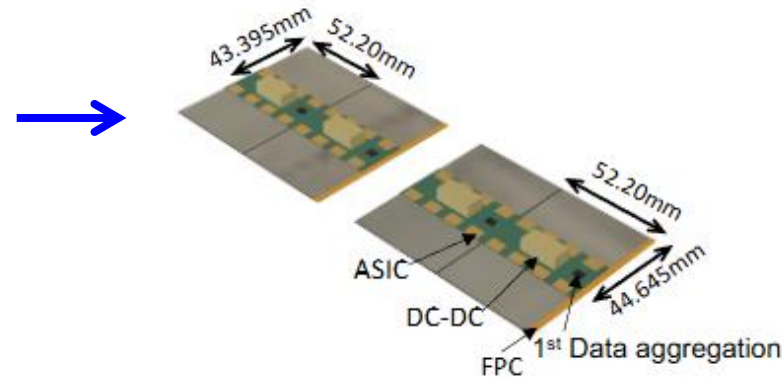
CEPC OTK Barrel Design (AC-LGAD Strips)

- ◆ AC-LGAD strip sensor is the choice for CEPC OTK baseline since it can provide both high-precision spatial resolution for momentum measurement and high-precision timing for particle identification.

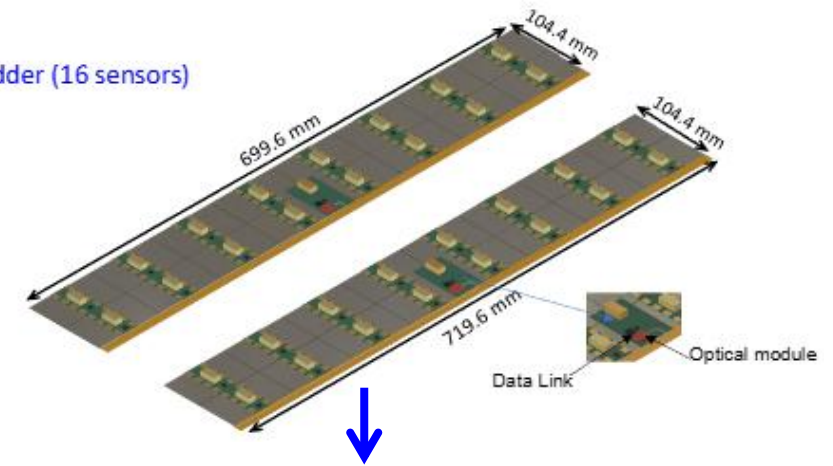
8-inch wafer



Module (2×2 sensors)



Ladder (16 sensors)



■ CEPC outer silicon tracker (OTK) utilizes AC-LGAD:

- For barrel: Sensor size: $4.34 \text{ cm} \times 5.22 \text{ cm}$
 $4.46 \text{ cm} \times 5.22 \text{ cm}$

Large size

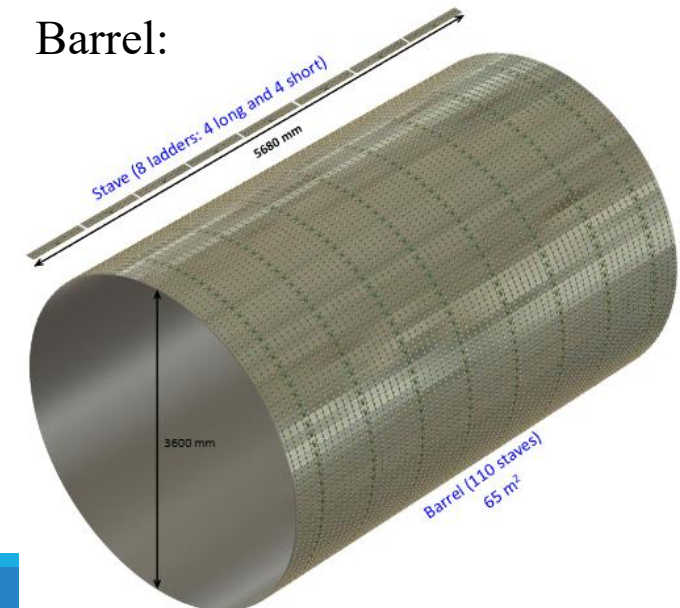
- Strip number per sensor: 512
- Strip pitch size: 100 μm

- **Spatial resolution: 10 μm**
- **Time resolution: 50 ps**

4D detector

- Power consumption: $\sim 300 \text{ mW/cm}^2$

Barrel:



Towards tracking application in CEPC

Scaling AC-LGAD to centimeter-scale strip lengths-essential for large-area tracking systems-introduces challenges:

➤ Increased strip capacitance:

increase noise and power consumption, worse timing performance

$$S/N \propto (1/\text{Capacitance}), \quad \sigma_{\text{jitter}} \propto t_{\text{rise}}/(S/N) \longrightarrow \sigma_{\text{jitter}} \propto \text{Capacitance}$$

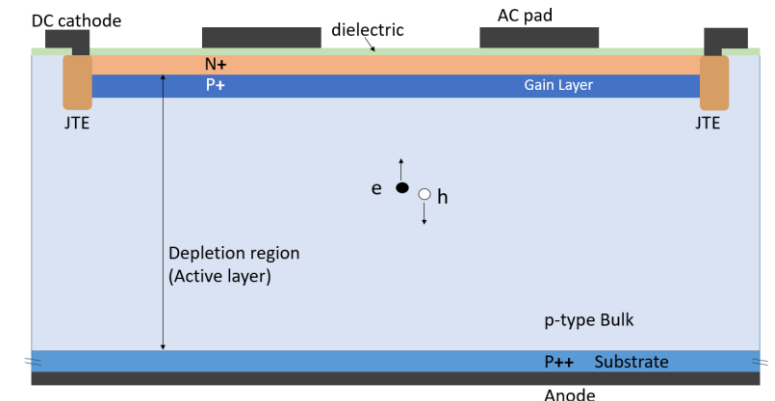
➤ Decreased signal performance

➤ Conduct structural and process simulations to design AC-LGAD that are suitable for use in tracking systems:

- Process parameter: n+ doping concentration, Dielectric material and thickness
- Structure parameter: metal pad-pitch size
- Isolation structures

➤ Fabricate and test of AC-LGAD prototype

- Sensors with different n+ doping concentration, metal pad-pitch size
- Timing and spatial resolution
- Radiation performance



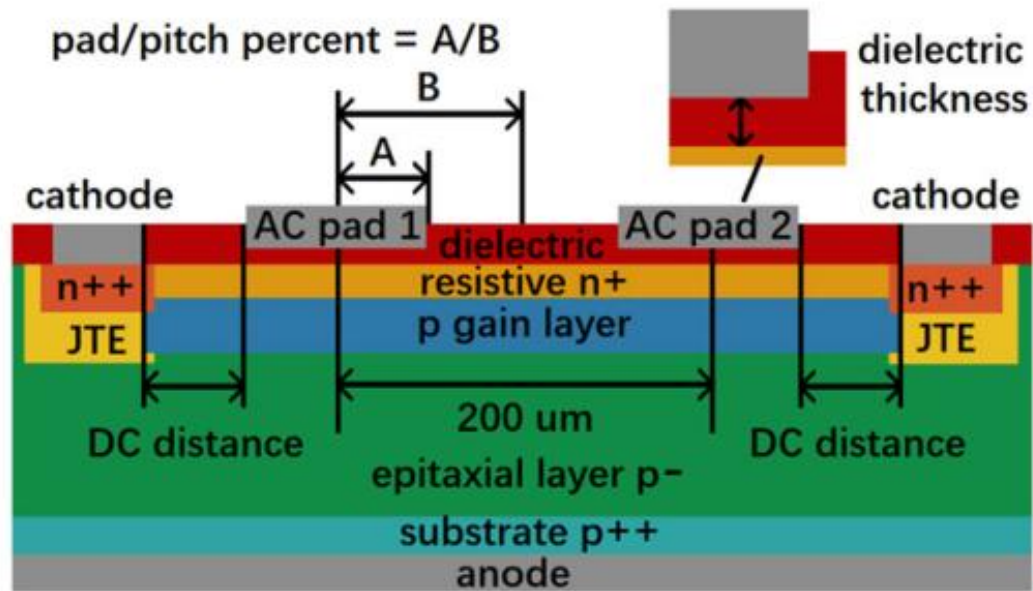
AC-LGAD simulation



◆ AC-LGAD sensor simulation: Optimization of process and structure parameters

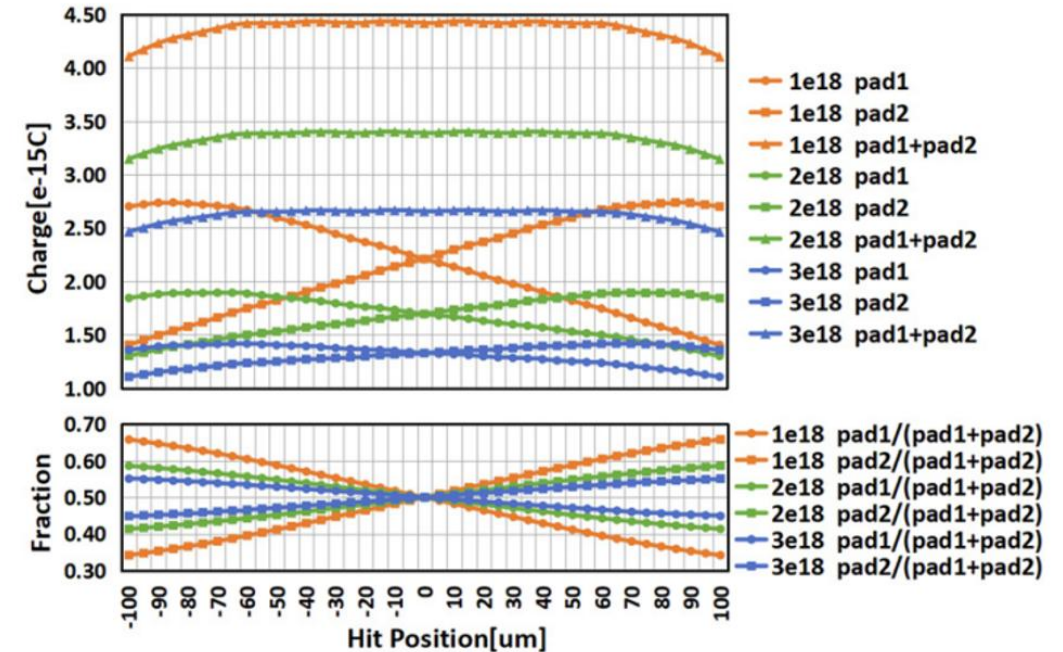
Process parameter: n⁺ layer dose, AC dielectric material and thickness

Structure parameter: Metal pad-pitch size



TCAD model of AC-LGAD for simulation

Design of AC-coupled low gain avalanche diodes (AC-LGADs): a 2D TCAD simulation study, JINST, 2022.9, DOI:[10.1088/1748-0221/17/09/C09014](https://doi.org/10.1088/1748-0221/17/09/C09014)

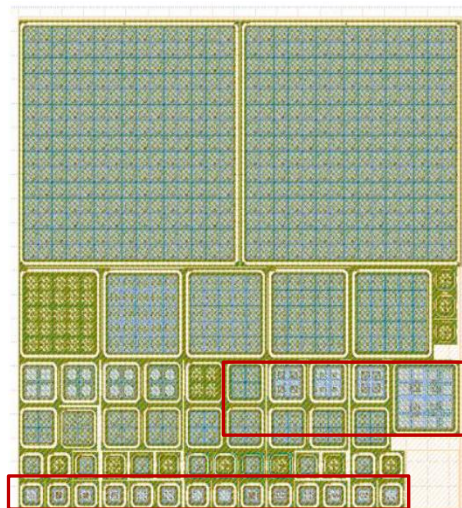


Lower n⁺ dose → Large resistivity → good spatial resolution

Less n⁺ dose (large resistivity), Large signal from begin and drop fast as changing position.

This means spatial resolution will be better as decreasing the n⁺ dose

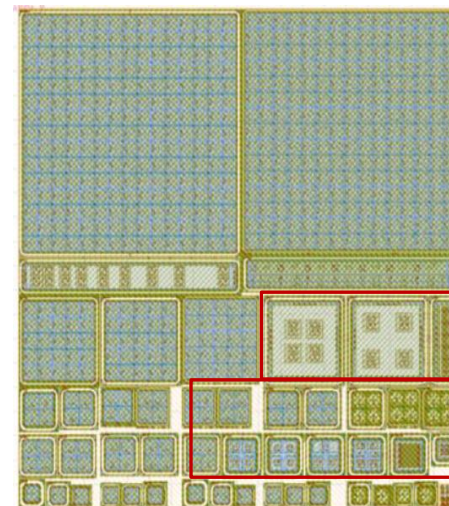
AC-LGAD R&D



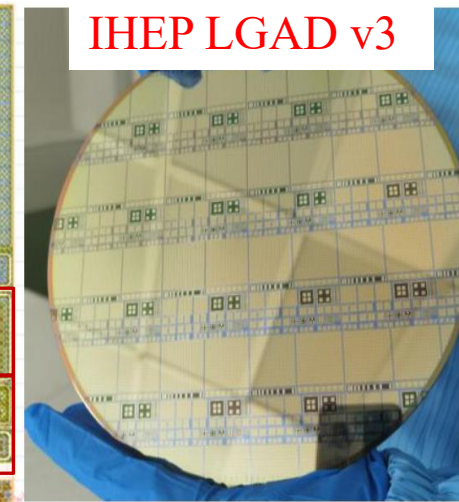
IHEP LGAD v2



In 2021



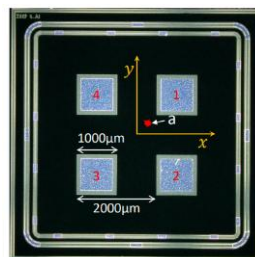
IHEP LGAD v3



In 2022

➤ Pixelated AC-LGAD

- With different pad-pitch size
1000-2000um
100-500um
100-200um
50-100um
- EPI thickness:50um
- Wafer: with different n+ dose: 10P to 0.2P



Process parameters(n+ dose) be studied.

The performance of large-pitch AC-LGAD with different N+ dose, Trans. Nucl. Sci. , 2023.6

➤ Pixelated and strip AC-LGAD

- With different pad-pitch size
1000-2000um pixel
100-250um strip
100-150um strip
50-100um strip
- EPI thickness:50um
- Wafer: with different n+ dose:0.2P to 0.01P



Strip sensor with different pad-pitch size be studied

The performance of AC-coupled Strip LGAD developed by IHEP, NIMA, Volume 1062, May 2024, 169203

Pixelated AC-LGAD test results

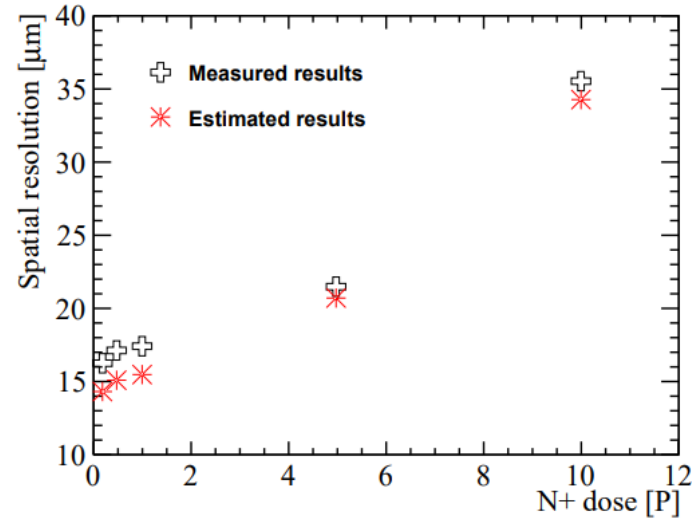
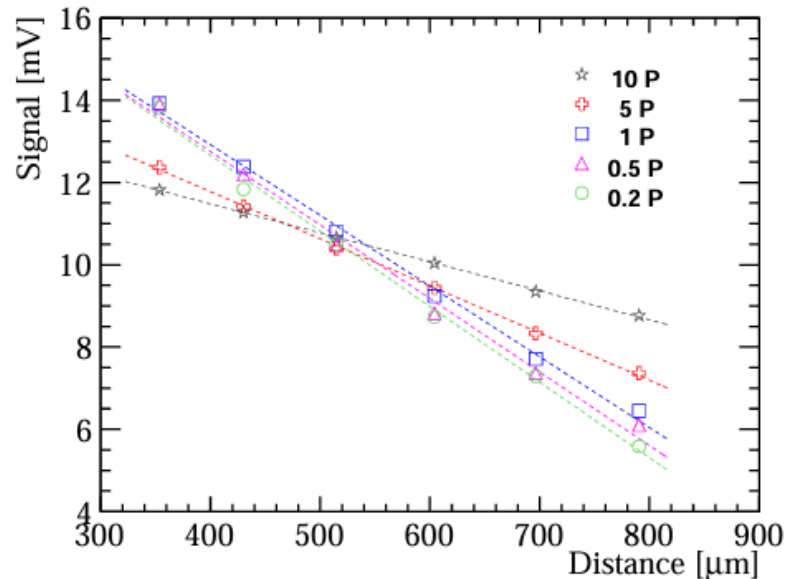
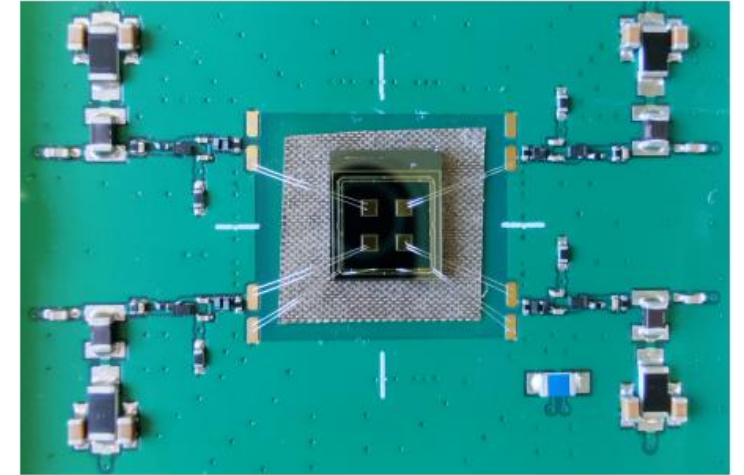
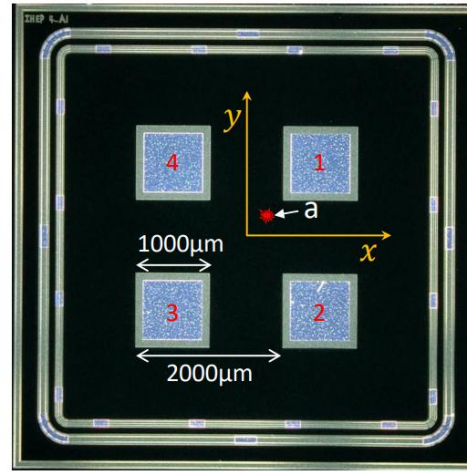
➤ AC-LGAD R&Dv1: pixelated AC-LGAD

Large pad-pitch size: 1mm-2mm

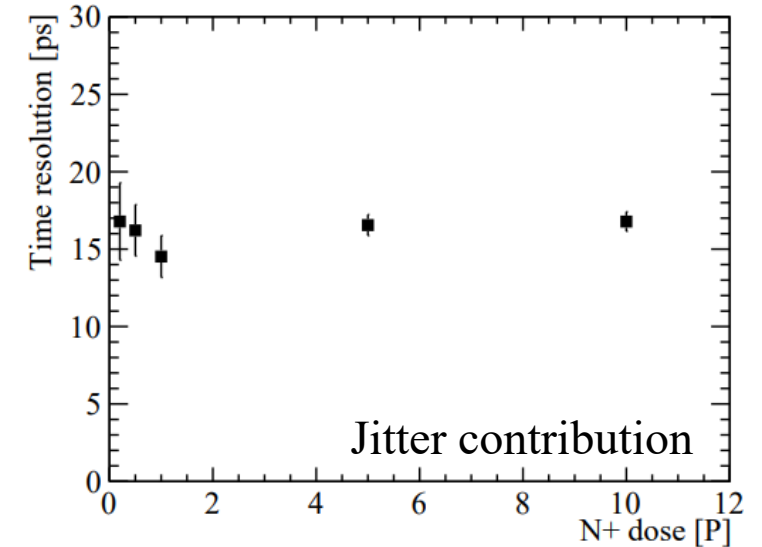
To study the process parameter

➤ Spatial resolution be better

as decreasing the n+ dose (10P to 0.2P)



Spatial resolution: 15μm

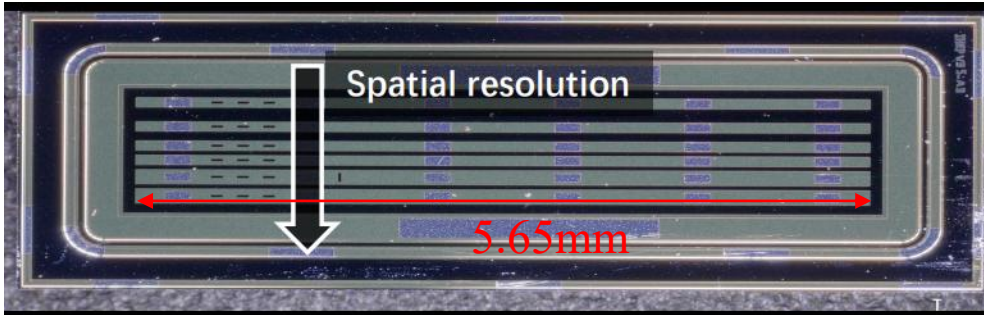


Timing resolution: 15-17ps

Strip AC-LGAD test

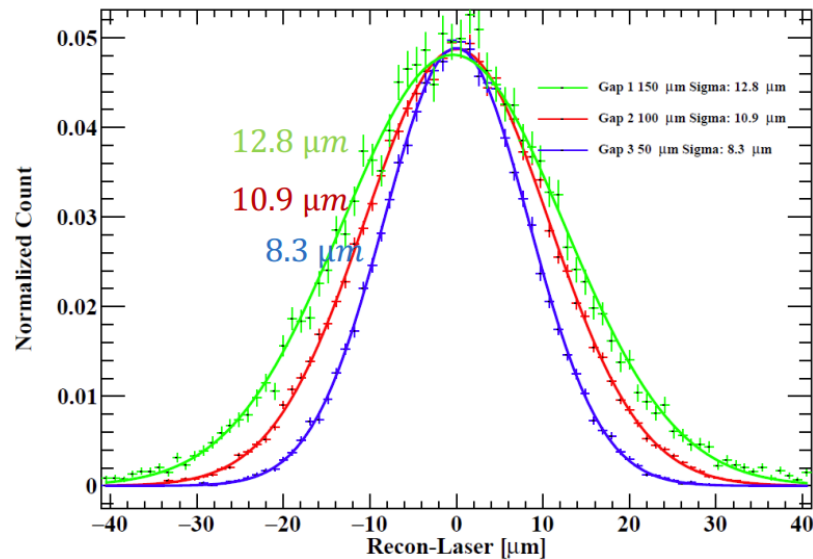
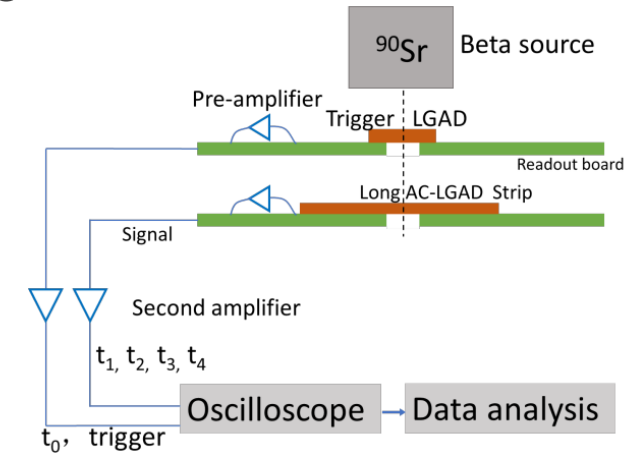
Spatial resolution: Laser testing

Timing resolution: Beta source test

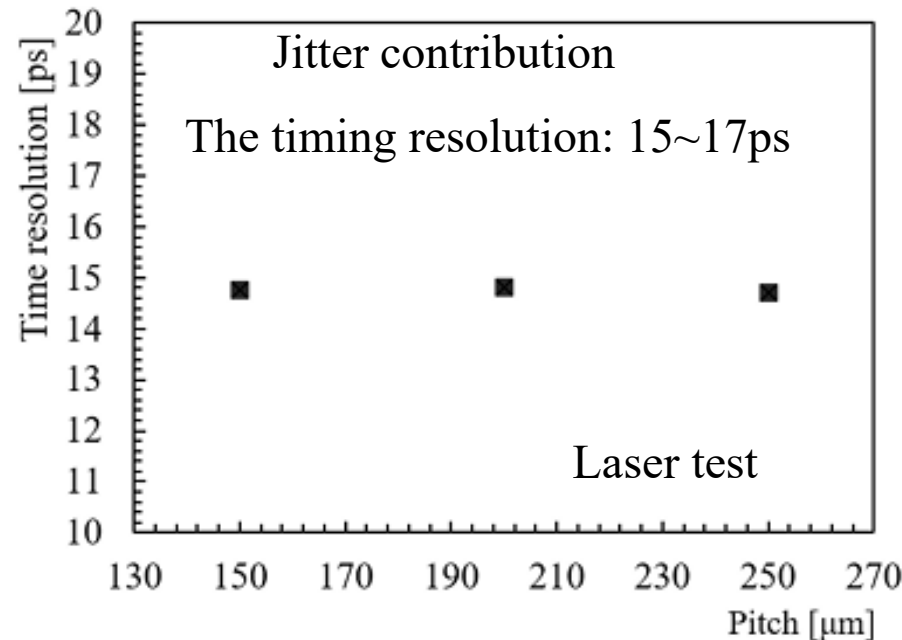


- Strip length 5.65mm
- pad-pitch size:
 - 100-250 μm
 - 100-200 μm
 - 100-150 μm

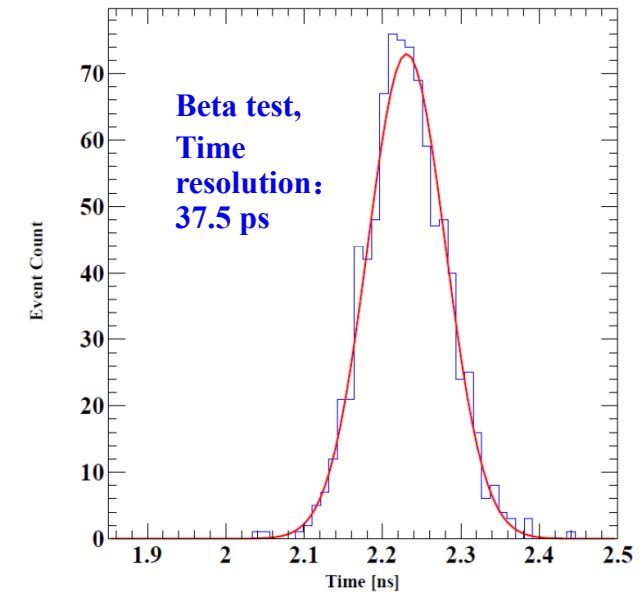
^{90}Sr test setup



**AC-LGAD with pitch size as 150 μm :
Best spatial resolution~8 μm (laser test)**

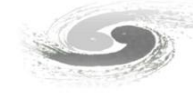


Landau and jitter contribution



**The performance of AC-coupled Strip LGAD developed by
IHEP, NIMA, Volume 1062, May 2024, 169203**

Strip AC-LGAD test: TID

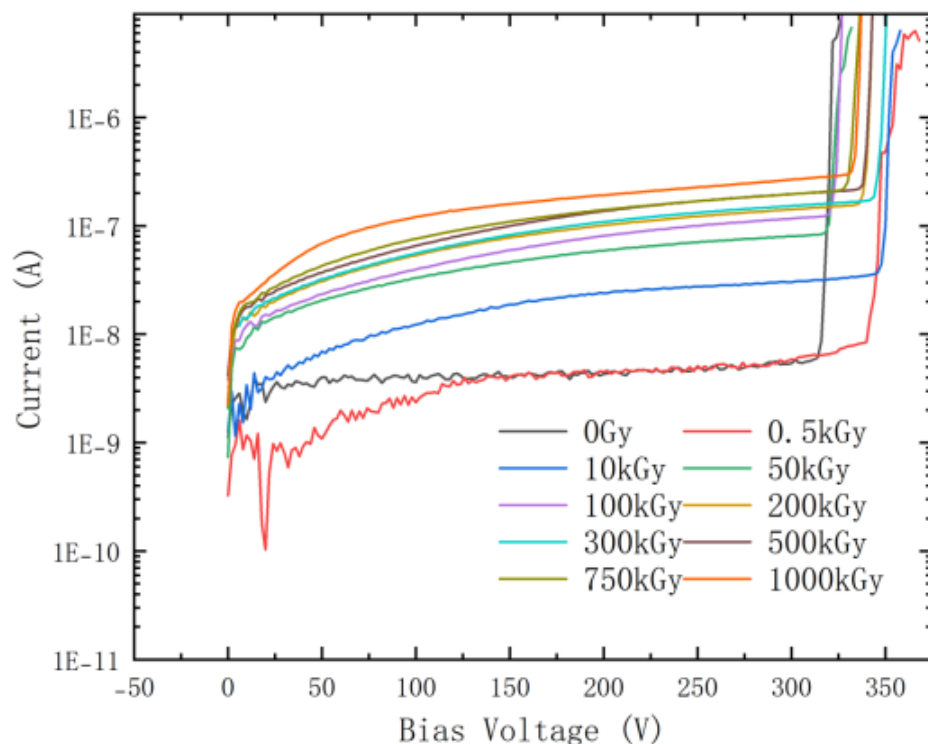


TID Impact on IHEP AC-LGAD Strip Sensors:

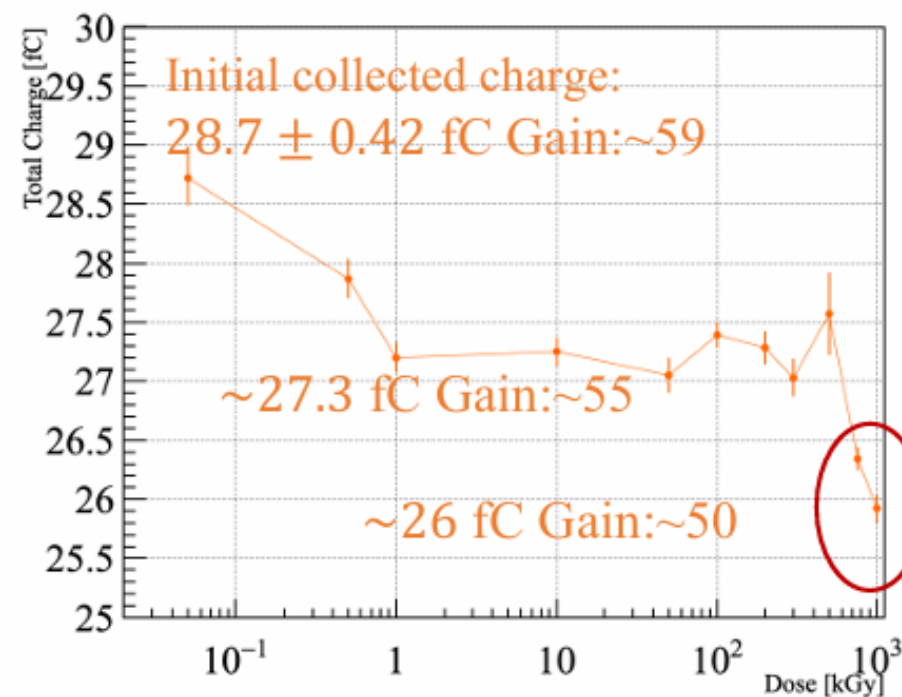
Irradiation: Multi-Rad 160 X-ray@40keV, up to 1MGy

Done by Weiyi Sun from IHEP, more details in his poster #57 this meeting

- Strip length 5.65mm
- pad-pitch size:
 - 100-250 μm
 - 100-200 μm
 - 100-150 μm**



- Leakage current increases by one order for sensors with TID dose as 1MGy



- Collected charge reduces, but very less up to 1MGy.

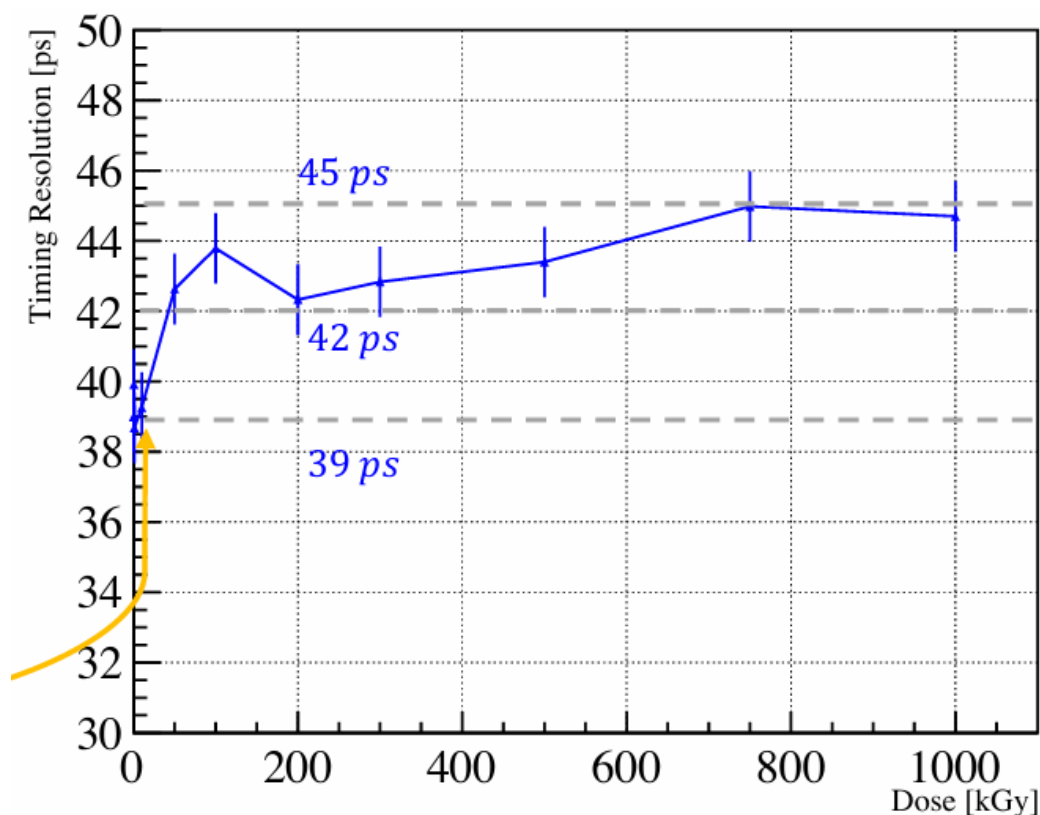
Strip AC-LGAD test: TID



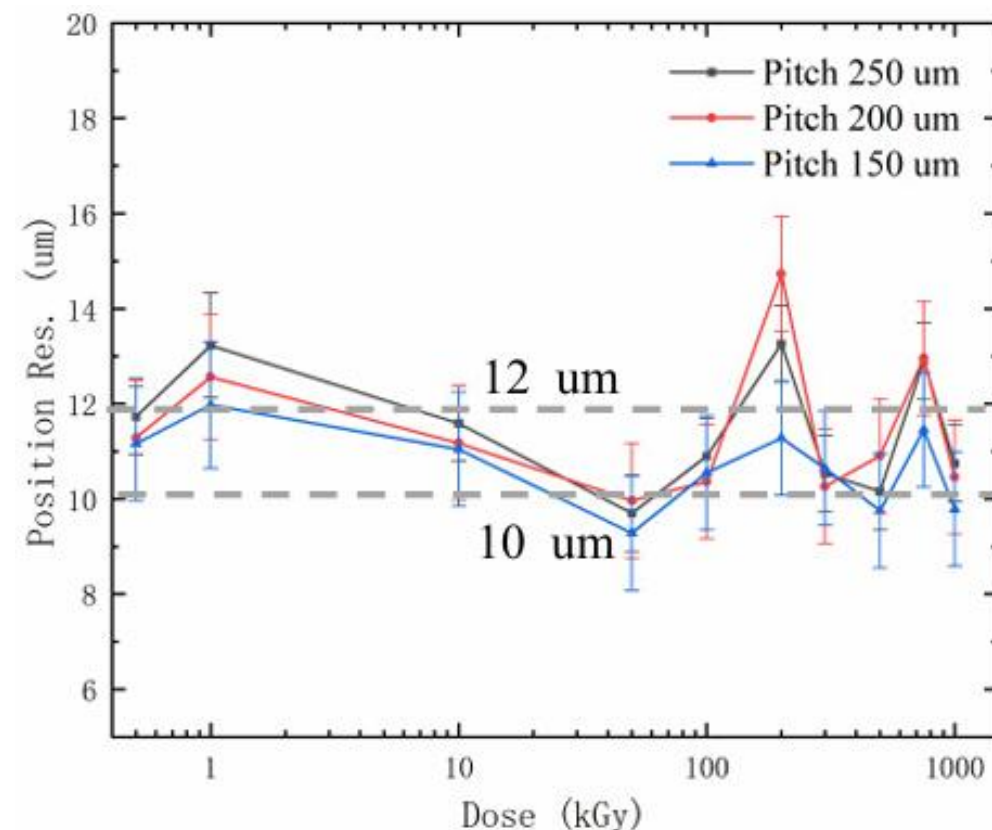
TID Impact on IHEP AC-LGAD

Done by Weiyi Sun from IHEP

Strip Sensors performance:



➤ Time resolution degrades from 38ps to 42ps.



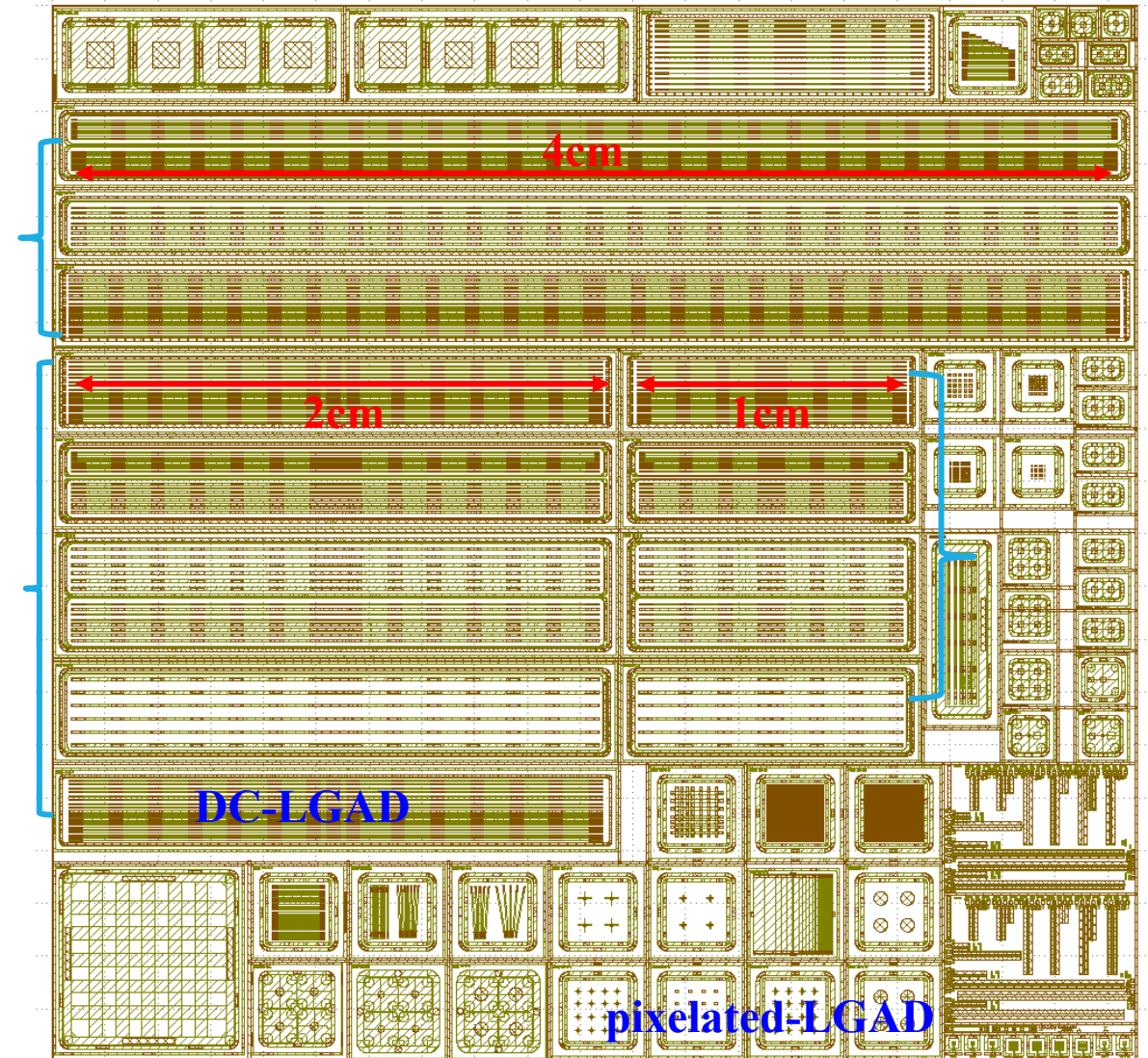
➤ Spatial resolution maintained in 10-12 μm up to 1 MGy

AC-LGAD with long strip

◆ AC-LGAD and DC-LGAD with long strip been submitted for fabrication in April 2025

- Strip lengths: 1 cm, 2 cm, and 4 cm
- Strip pitch sizes: 100 μm , 200 μm , and 500 μm
- Electrode widths: 25 μm , 50 μm , and 100 μm
- Isolated structure design and EPI thickness(50 μm , 80 μm) to reduce sensor capacitance
- Process design optimization: n+ doping concentration

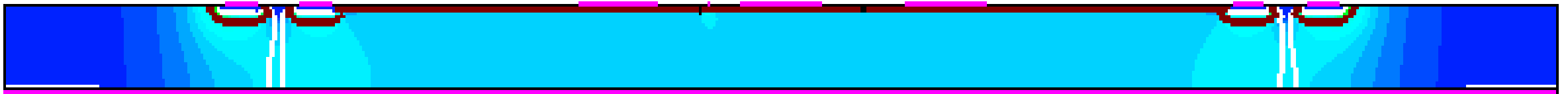
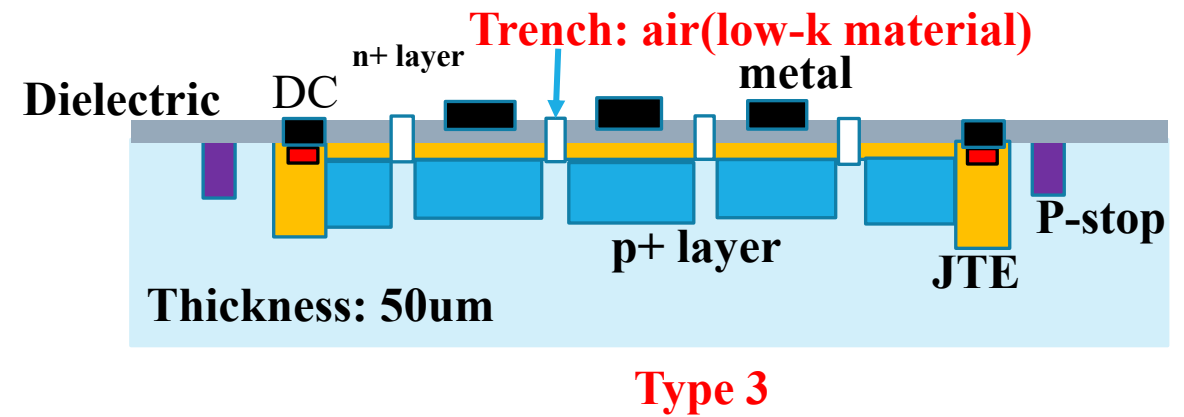
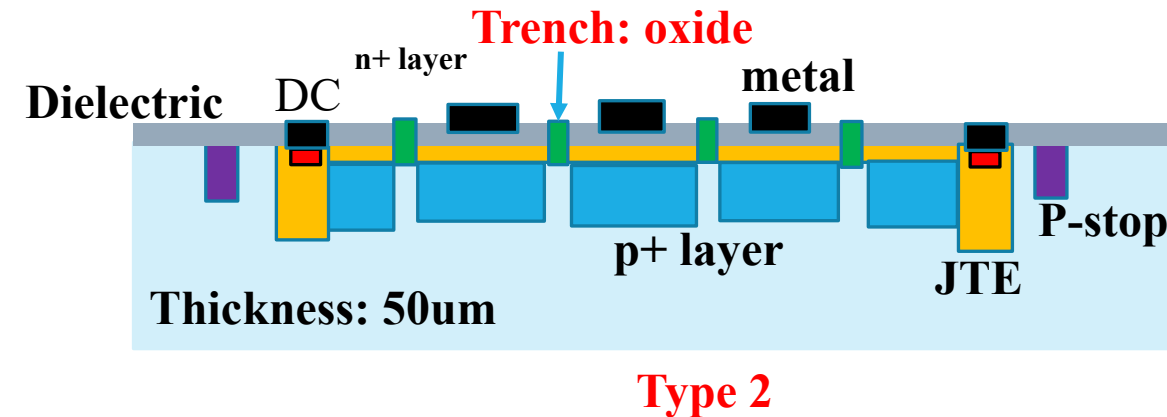
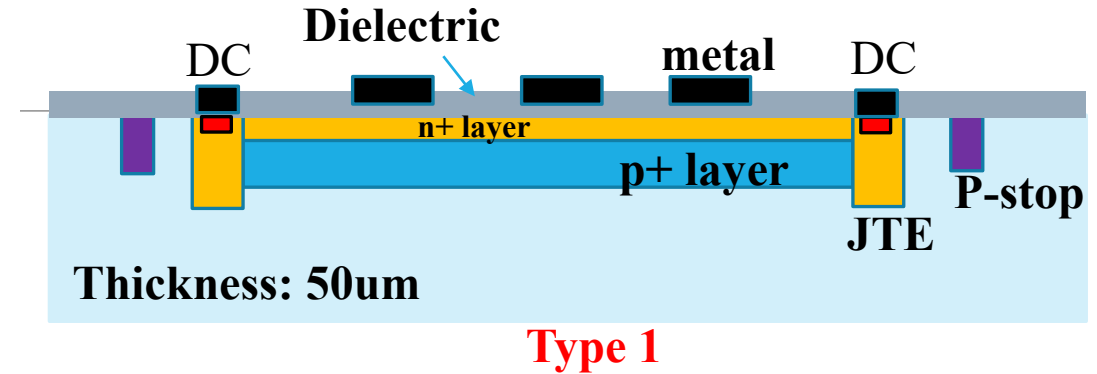
◆ Sensors will be delivered in December



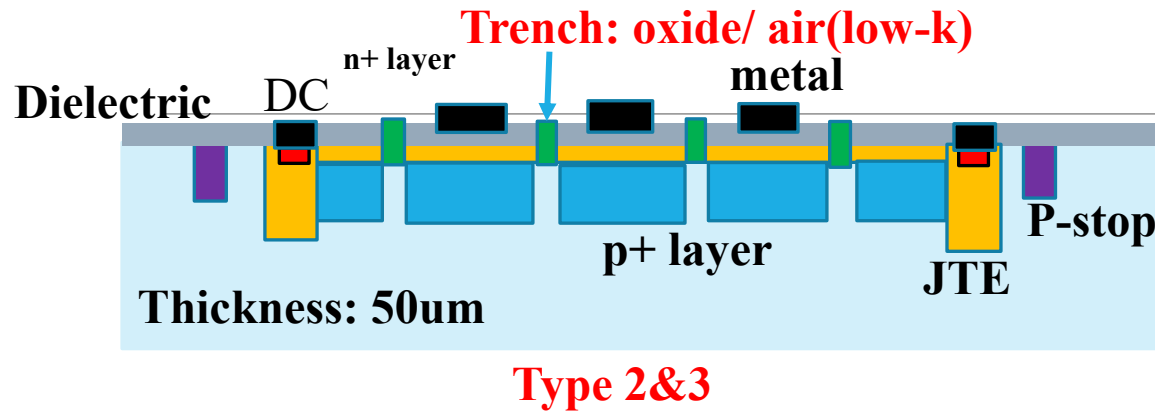
Isolated AC-LGAD simulation and design



- Trench isolation structure be added to reduce the bulk and inner-strip capacitance, critical for power consumption.
- Sensors with 3 types of structures be simulated using TCAD tools.
- Sensor performance been simulated:
I-V; C-V: bulk capacitance, coupling capacitance, inter-strip capacitance;

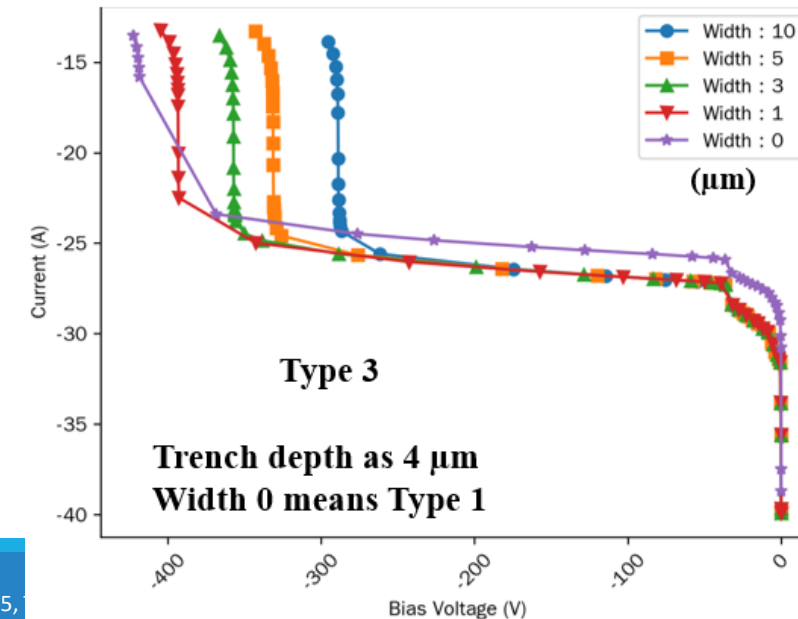
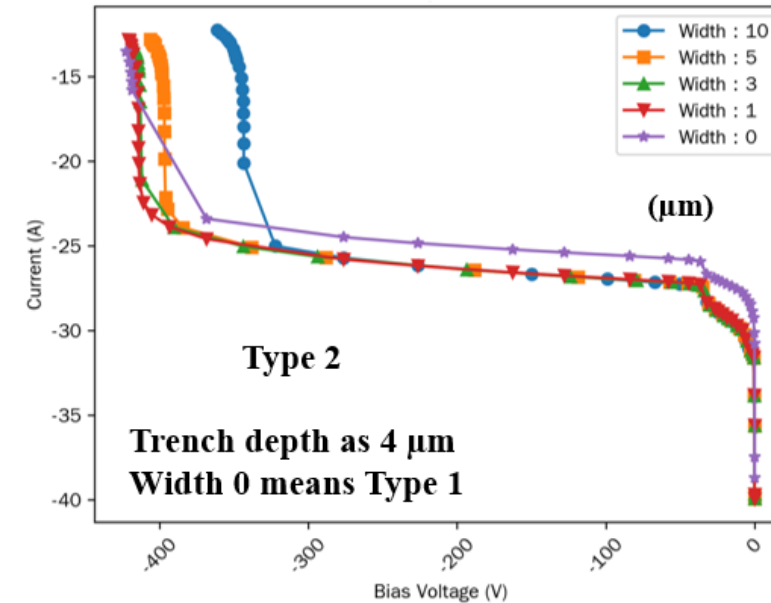


Isolated AC-LGAD Simulation and Design



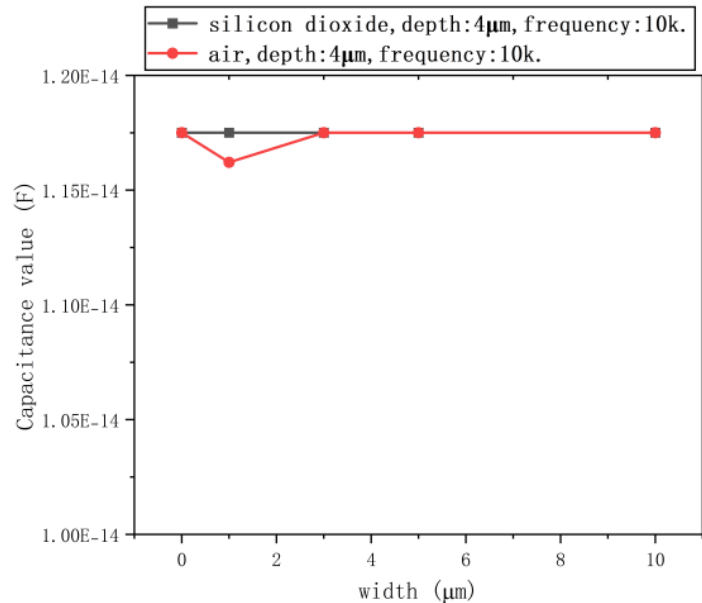
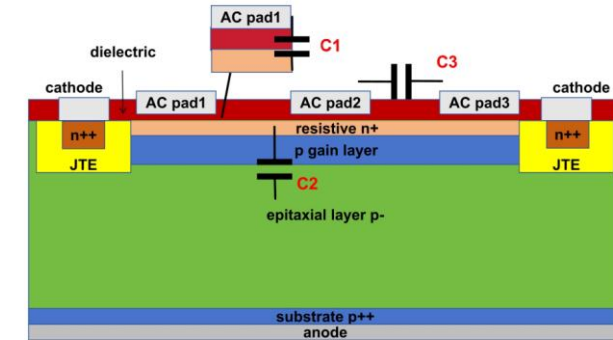
Trench width:

- I-V performance will change as changing the trench width[type 2 and type 3].
- Breakdown voltage V_{bd} and operation voltage will decrease as increasing the trench width since the electrical field changes

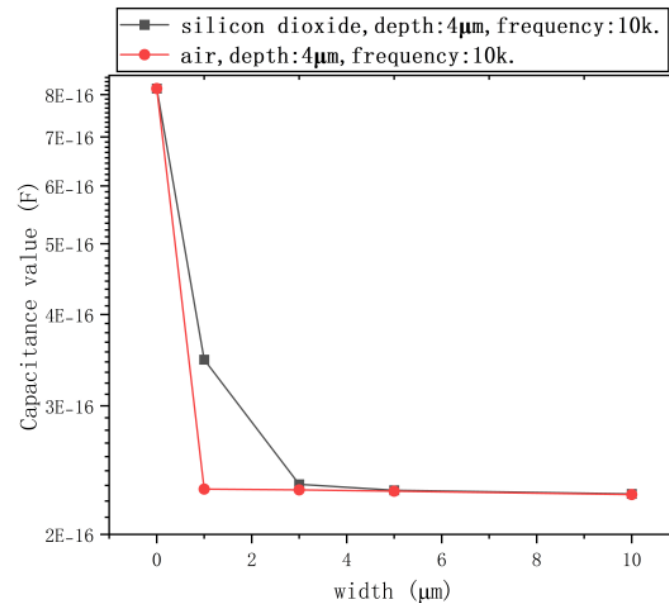


Isolated AC-LGAD Simulation and Design

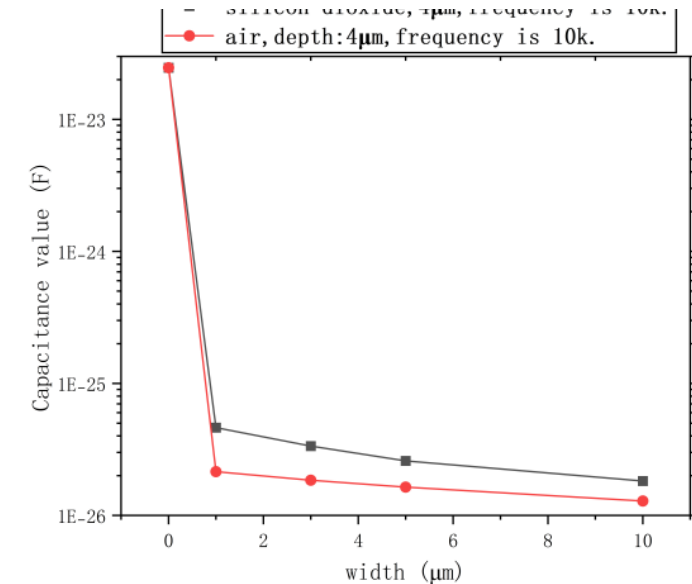
- Depleted bulk capacitance and inter-strip capacitance significantly reduced for AC-LGAD with Si oxide and vacuum(low-k) isolation structures.



(a) Coupling capacitance



(b) Bulk capacitance

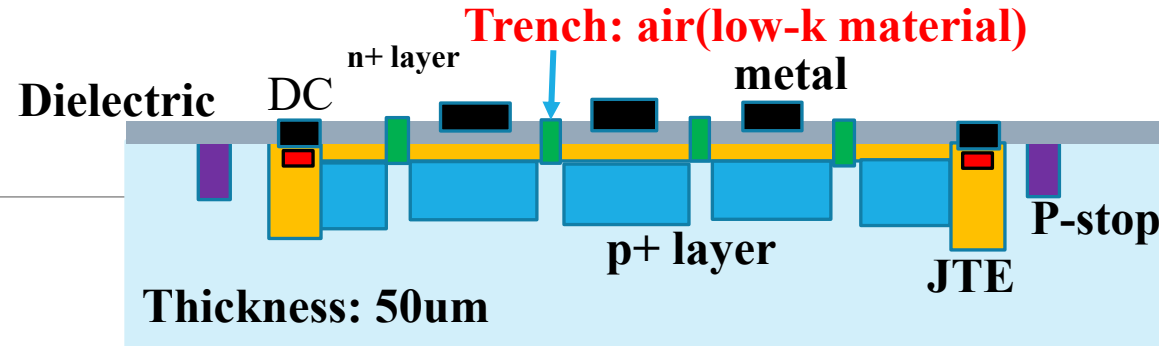


(c) Inter-pad capacitance

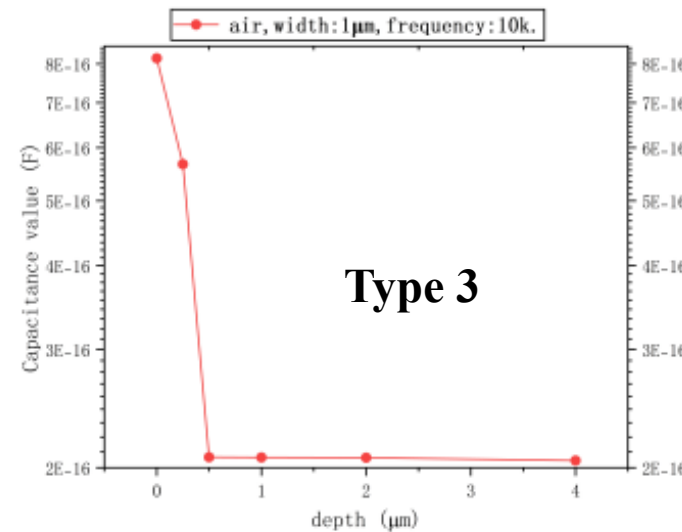
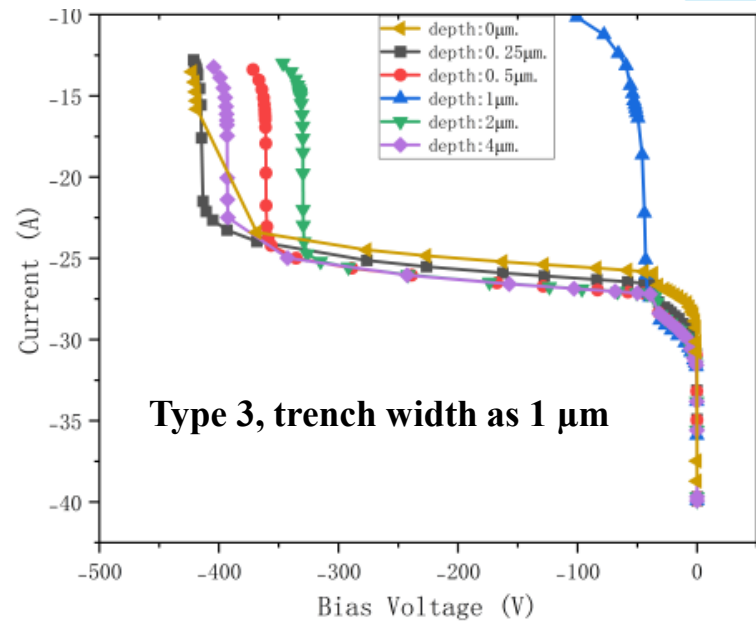
Isolated AC-LGAD Simulation and Design



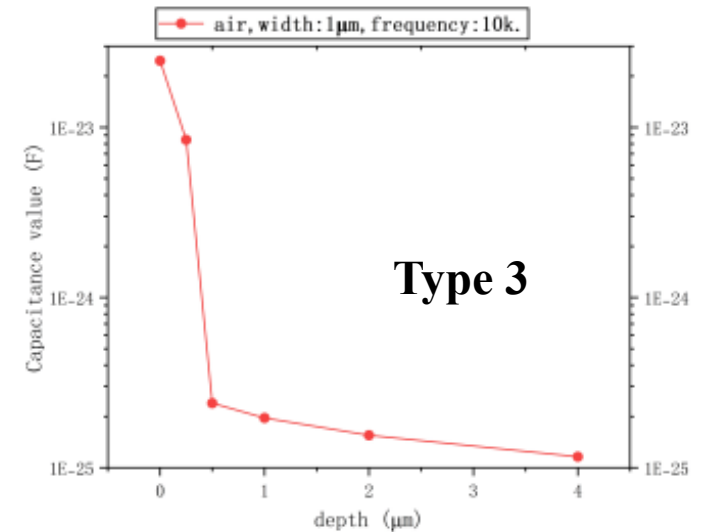
Trench depth



Type 3



bulk capacitance



Inter-strip capacitance

- Trench isolation depth be simulated and IV changes as changing the trench depth.

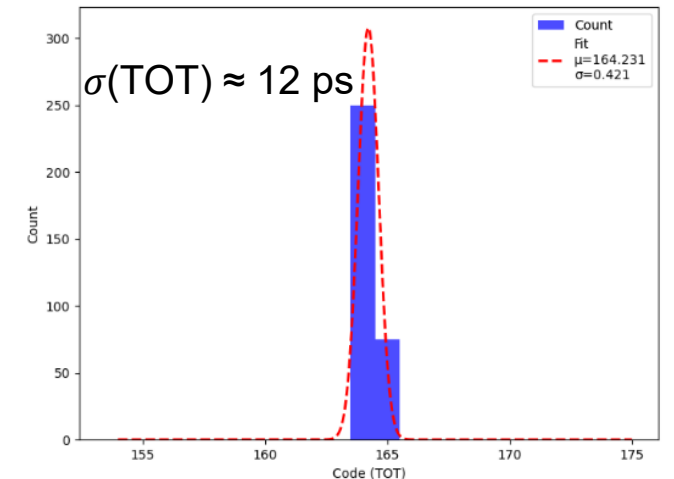
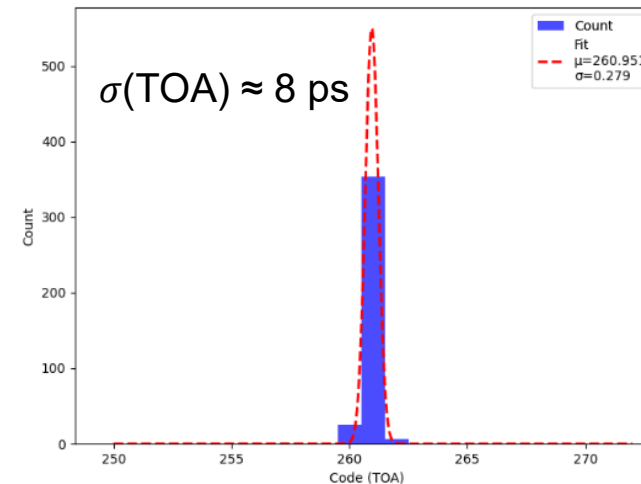
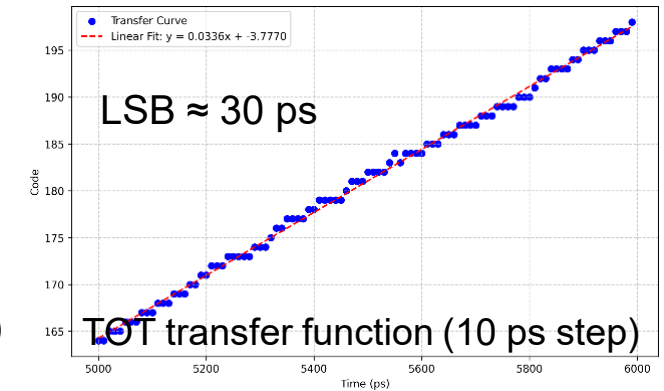
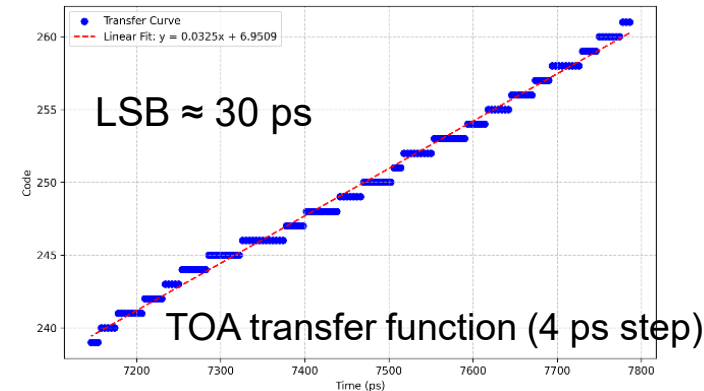
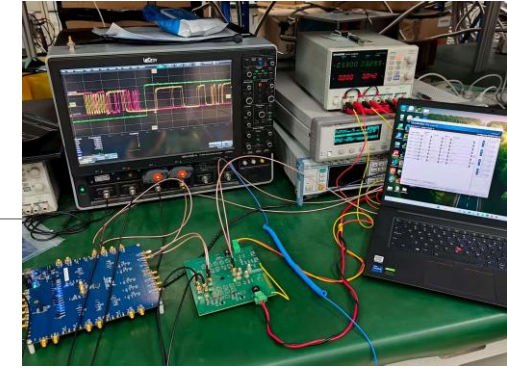
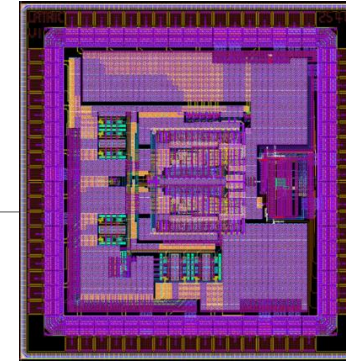
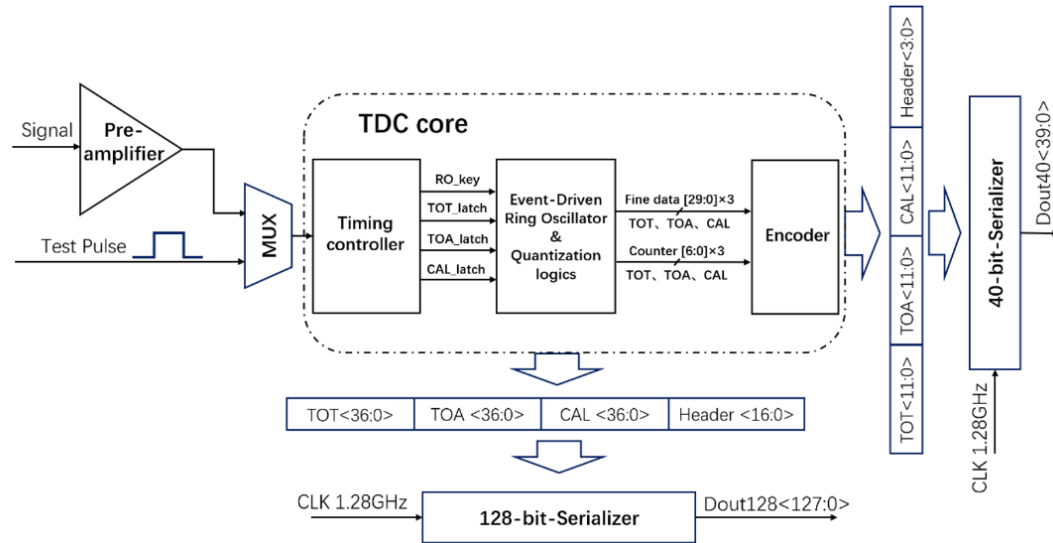
- Depleted bulk capacitance and inter-strip capacitance significantly reduced for AC-LGAD as the depth increasing.

LGAD Readout ASIC (LATRIC)

➤ The first LGAD readout ASIC prototype, LATRIC-V0, submitted for tape-out in April, was delivered in August:

- The ASIC integrates a pre-amplifier, a discriminator, a TDC, and a serializer for data output.
- The LSB is 29.8 ps, meeting the 30 ps design goal.
TDC power consumption is 0.1 mA (1.2 V) @ 0.5 MTPS (Mega-Trigger Per Second), 0.3 mA @ 1 MTPS, and 0.5 mA @ 2 MTPS.

➤ The 8-channel LATRIC-V1 was submitted for tape-out in October.

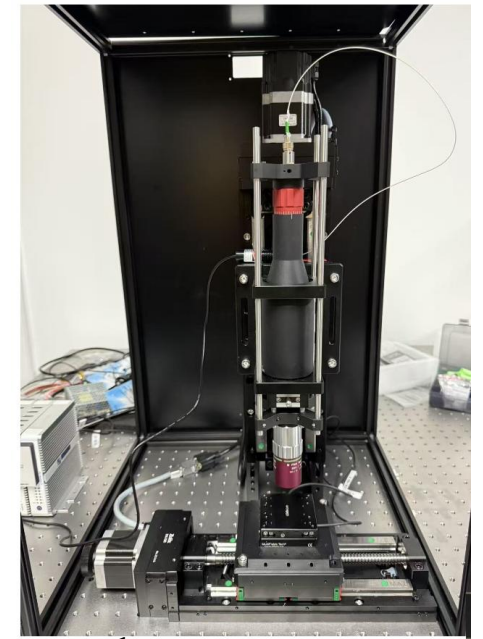
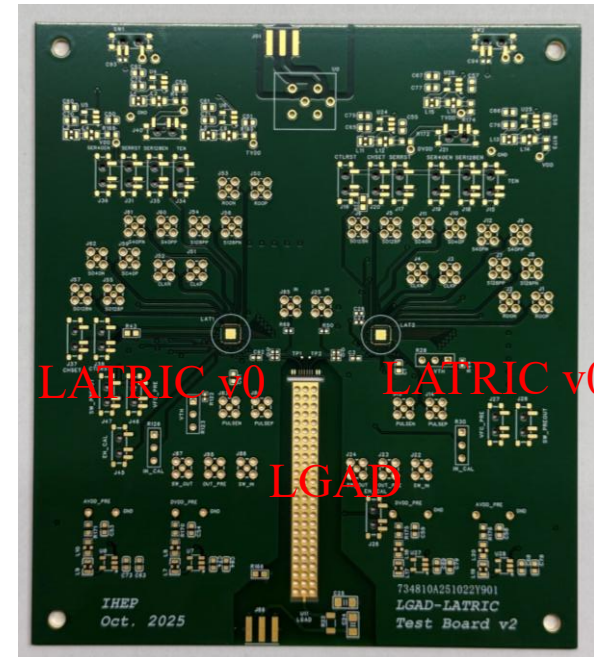


Summary and Next step

Summary

- For AC-LGAD Structure and process parameters: Simulation, design and fabrication and test of prototype
- IHEP AC-LGAD Sensor with optimized structure and process parameters show good timing(<40ps) and spatial resolution(<10um), including TID results.
- AC-LGAD with long strip is simulated and designed, fabrication ongoing. Will be delivered in December.
- ASIC for readout AC-LGAD is fabricated and tested. Timing performance~10ps

- Performance evaluation of AC-LGAD and DC-LGAD with 1cm, 2cm, 4cm long strips
- Test of LGAD + ASIC
[LATRIC v0 LGAD readout ASIC]



laser test setup

- Beam test is planned in middle of 2026 [CERN PS]

Thanks

Goal: Develop LGAD based silicon sensors with a spatial resolution better than 10 μm and a timing resolution in the range of 30-50 ps as Timing Tracker for Future Electron Collider

	Participants
IHEP	Institute of high energy physics, Chinese Academy of Sciences
IME	Institute of Microelectronics, Chinese Academy of Sciences
JSI	Jozef Stefan Institute, Ljubljana
USP	University of São Paulo
UCG	University of Montenegro
SDU	Shandong University
SJTU	Shanghai Jiao Tong University
ZZU	Zhengzhou University

DRD3 WG2 Project: LGAD based Timing Tracker Development for Future Electron Collider

Research package

1. AC-LGAD simulation and design
 2. AC-LGAD fabrication
 3. AC-LGAD lab testing: IV, CV, timing resolution, spatial resolution
 4. AC-LGAD beam test
 5. Radiation performance study (TID, neutron, proton)
 6. Position reconstruction methods
 7. The applications of LGAD for other particle experiment and outside of particle physics
- Explore the AC-LGAD's application as photo detector or X-ray detector

CDS: <https://cds.cern.ch/record/2918306>

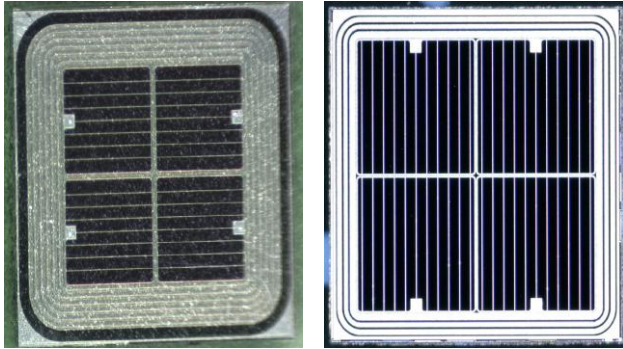
Contact: Mei Zhao, zhaomei@ihep.ac.cn

Back up

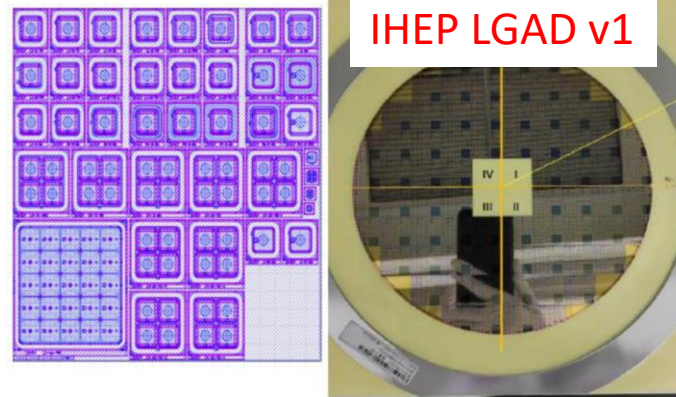
LGAD Development at IHEP



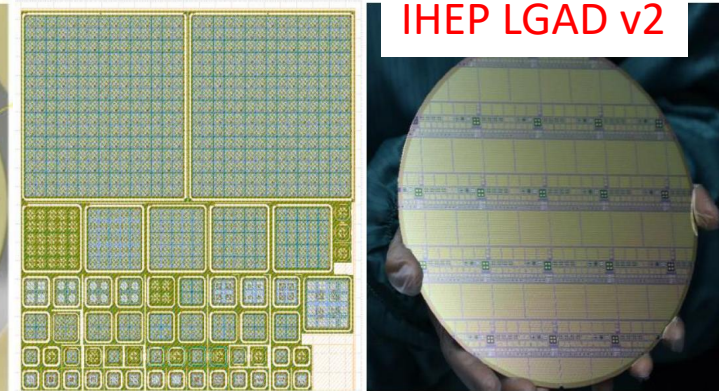
IHEP-NDL(2019)



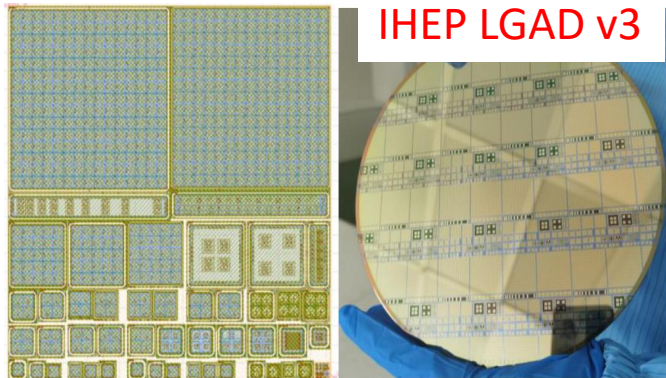
IHEP LGAD v1 (2020.9)



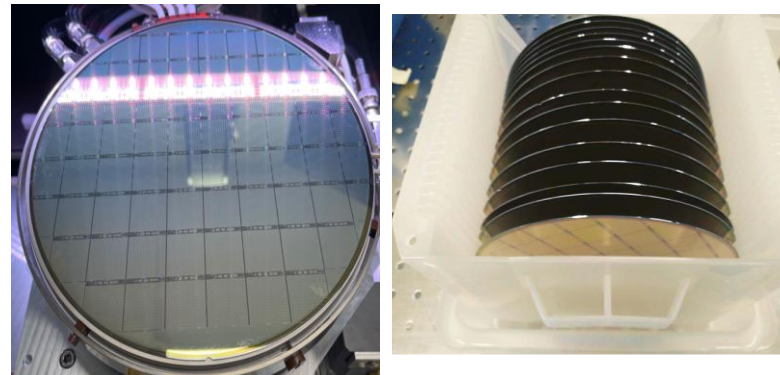
IHEP LGAD v2 (2021.6)



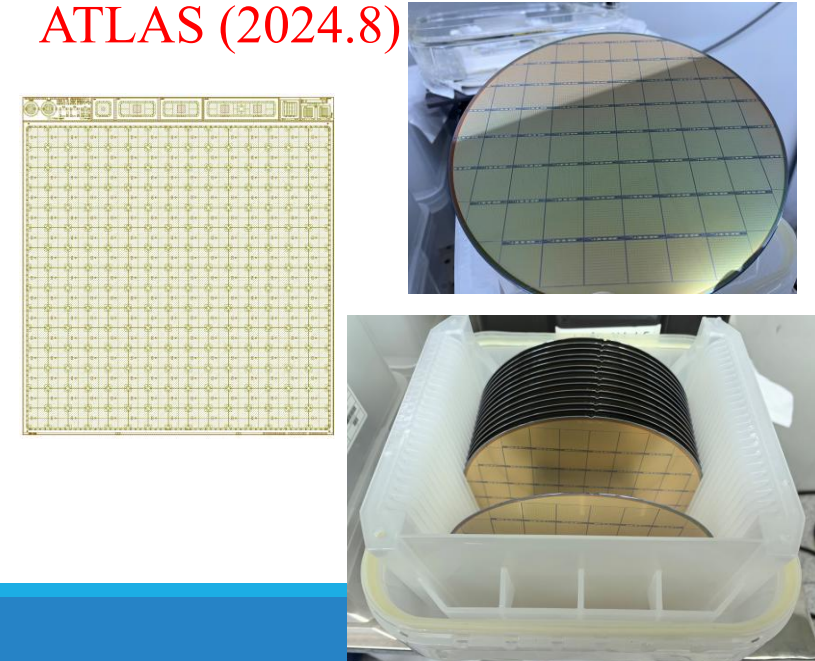
IHEP LGAD v3 (2022.5)

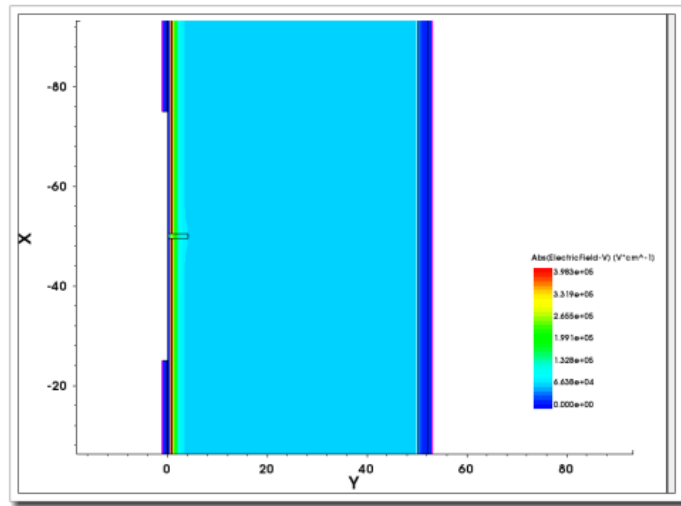


Pre-production for ATLAS (2023.7)

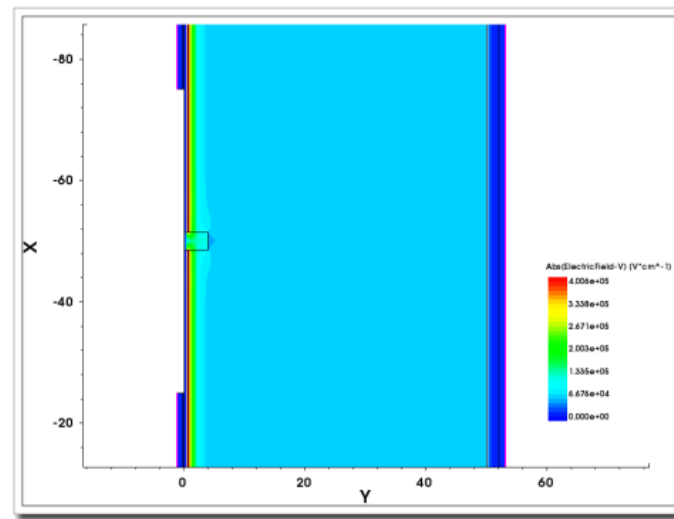


Mass production for
ATLAS (2024.8)

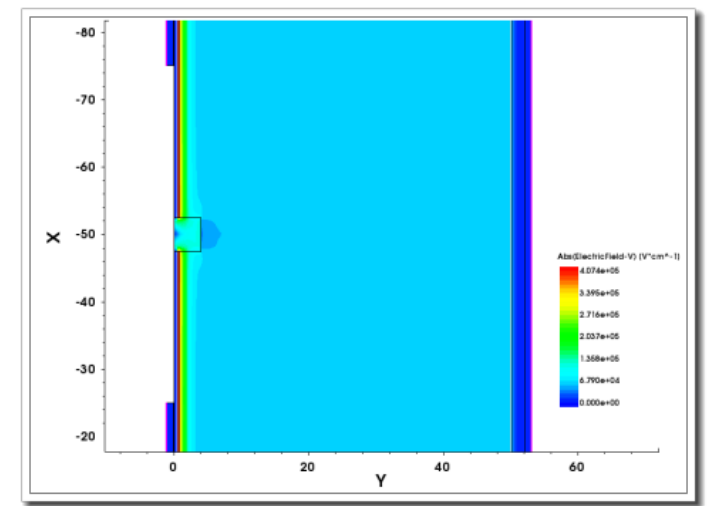




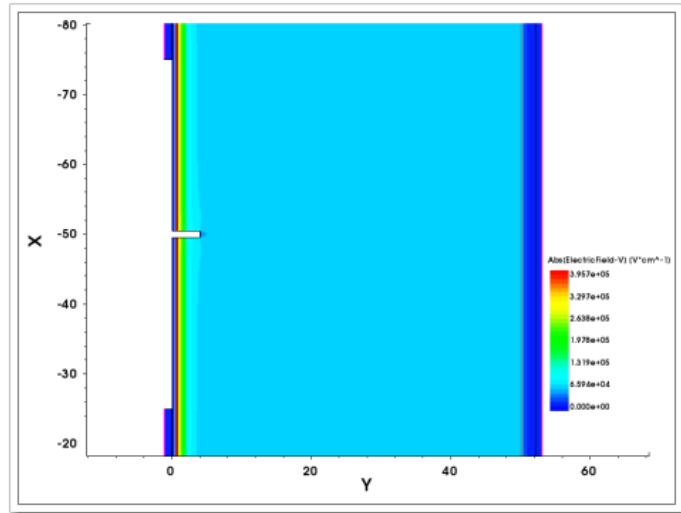
(a) SiO₂, 1 μm



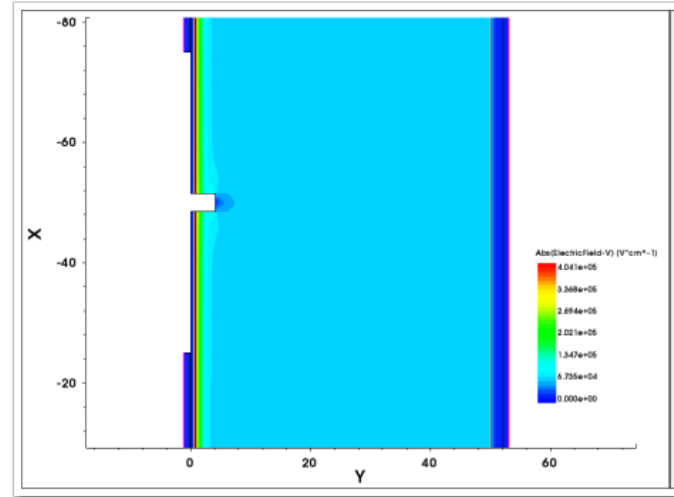
(b) SiO₂, 3 μm



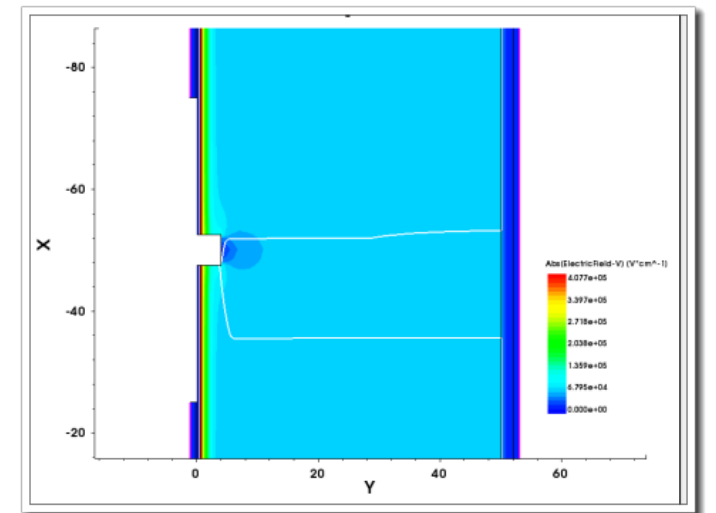
(c) SiO₂, 5 μm



(d) Air, 1 μm



(e) Air, 3 μm



(f) Air, 5 μm